

P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary (Typ @ $V_{GS} = -4.5V$, $T_A = +25$ °C)

| BV _{DSS} | R _{DS(ON)} | $\mathbf{Q}_{\mathbf{g}}$ | Q_{gd} | ID |
|-------------------|---------------------|---------------------------|----------|-------|
| -12V | 65mΩ | 9nC | 2.4nC | -3.2A |

Features and Benefits

- Built-in G-S Protection Diode against ESD 2kV HBM
- Ultra Small 0.8mm x 0.8mm Package
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Description and Applications

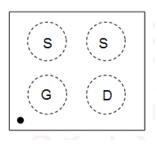
This new generation MOSFET has been designed to minimize the onstate resistance $(R_{\text{DS}(\text{ON})})$ and yet maintain superior switching performance, making it ideal for high efficiency power management applications. It is a High performance MOSFET in ultra-small 0.8mm x0.8mm package.

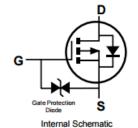
- Portable Applications
- Load Switch
- Power Management Functions

Mechanical Data

- Case: X2-WLB0808-4
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- UBM Opening: 203μm







Top View

Ordering Information (Note 4)

| Part Number | Case | Packaging |
|---------------|--------------|------------------|
| DMP1100UCB4-7 | X2-WLB0808-4 | 3000/Tape & Reel |

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



9W = Product Type Marking Code YM = Date Code Marking Y or \overline{Y} = Year (ex: D = 2016) M or \overline{M} = Month (ex: 9 = September)

Date Code Key

| Year | 201 | 6 | 2017 | | 2018 | 20 | 19 | 2020 | | 2021 | 2 | 2022 |
|-------|-----|-----|------|-----|------|-----|-----|------|-----|------|-----|------|
| Code | D | | Е | | F | (| 3 | Н | | ı | | J |
| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
| Code | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 0 | N | D |



Maximum Ratings

| Characteristic | Symbol | Value | Unit | |
|--|----------------------------------|----------------|--------------|---|
| Drain-Source Voltage | V_{DSS} | -12 | V | |
| Gate-Source Voltage | V _{GSS} | ±8 | V | |
| Continuous Source Current @ V _{GS} = -4.5V (Note 5) | $T_A = +25$ °C $T_A = +70$ °C | I _D | -2.5 -2.0 | Α |
| Continuous Source Current @ V _{GS} = -4.5V (Note 6) | $T_A = +25$ °C $T_A = +70$ °C | I _D | -3.2 -2.6 | A |
| Pulsed Drain Current (Pulse Duration 10µs, Duty Cycle ≤1% | I _{DM} | -13 | A | |
| Continuous Source-Drain Diode Current | I _S | -1.2 | A | |

Thermal Characteristics

| Characteristic | Symbol | Value | Unit |
|--|-----------------------------------|-------------|------|
| Total Power Dissipation (Note 5) | P _D | 0.67 | W |
| Thermal Resistance, Junction to Ambient (Note 5) | $R_{	heta JA}$ | 187 | °C/W |
| Total Power Dissipation (Note 6) | P _D | 1.1 | W |
| Thermal Resistance, Junction to Ambient (Note 6) | $R_{	heta JA}$ | 117 | °C/W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -55 to +150 | °C |

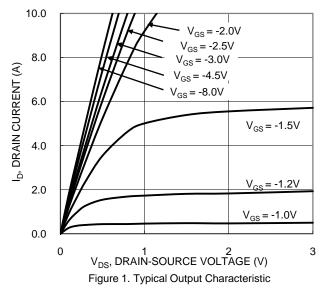
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition | | | |
|-----------------------------------|---------------------|-------|-------------------------------------|--------------------------------------|------|---|--|--|--|
| OFF CHARACTERISTICS (Note 7) | | | | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | -12 | - | - | V | $V_{GS} = 0V, I_{D} = -250\mu A$ | | | |
| Zero Gate Voltage Drain Current | I _{DSS} | - | - | -1 | μA | $V_{DS} = -12V, V_{GS} = 0V$ | | | |
| Gate-Body Leakage | I _{GSS} | - | - | ±10 | μA | $V_{GS} = \pm 8V, V_{DS} = 0V$ | | | |
| ON CHARACTERISTICS (Note 7) | | | | | | | | | |
| Gate Threshold Voltage | V _{GS(TH)} | -0.35 | -0.55 | -0.8 | V | $V_{DS} = V_{GS}$, $ID = -250\mu A$ | | | |
| Static Drain-Source On-Resistance | Rds(on) | - | 65 80 90 115 135 150 | 83 96 150 170 300 400 | mΩ | $V_{GS} = -4.5V, I_D = -3A$ $V_{GS} = -2.5V, I_D = -2A$ $V_{GS} = -1.8V, I_D = -1A$ $V_{GS} = -1.5V, I_D = -1A$ $V_{GS} = -1.4V, I_D = -1A$ $V_{GS} = -1.3V, I_D = -1A$ | | | |
| Forward Transfer Admittance | Y _{fs} | - | 6.5 | - | S | $V_{DS} = -4V, I_{S} = -1.5A$ | | | |
| Body Diode Forward Voltage | V_{SD} | - | -0.7 | - | V | $V_{GS} = 0V, I_{S} = -1.5A,$ | | | |
| DYNAMIC CHARACTERISTICS (Note 8) | | | | | | | | | |
| Input Capacitance | C _{iss} | - | 680 | 820 | pF | $V_{DS} = -6V, V_{GS} = 0V,$ | | | |
| Output Capacitance | C _{oss} | - | 220 | 290 | pF | $V_{DS} = -6V, V_{GS} = 6V,$ -f = 1.0MHz | | | |
| Reverse Transfer Capacitance | C_{rss} | - | 205 | 280 | pF | 1 - 1.00012 | | | |
| Gate Resistance | R_g | - | 11.2 | 17 | Ω | $V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$ | | | |
| Total Gate Charge | Q_g | - | 9.0 | 14 | nC | $V_{GS} = -4.5V$. $V_{DS} = -6V$. | | | |
| Gate-Source Charge | Q_{gs} | - | 1.0 | - | nC | $V_{GS} = -4.5V, V_{DS} = -6V,$ $-1_{D} = -2A$ | | | |
| Gate-Drain Charge | Q_gd | - | 2.6 | - | nC | 10 – -27 | | | |
| Turn-On Delay Time | $t_{D(ON)}$ | - | 4.4 | 9 | ns | | | | |
| Turn-On Rise Time | t _R | - | 10.1 | - | ns | $V_{DD} = -4V$, $I_D = -2A$ | | | |
| Turn-Off Delay Time | t _{D(OFF)} | - | 22 | 33 | ns | $V_{GEN} = -4.5V$, $R_g = 1\Omega$, $R_L = 3\Omega$ | | | |
| Turn-Off Fall Time | t _F | - | 20 | - | ns | | | | |

Notes:

- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
- 7. Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to production testing.





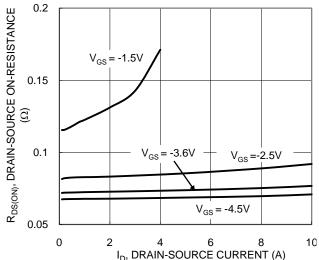


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

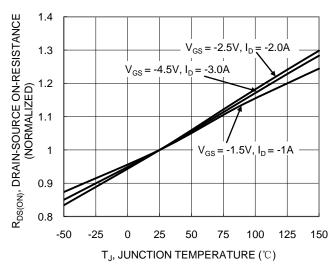


Figure 5. On-Resistance Variation with Junction Temperature

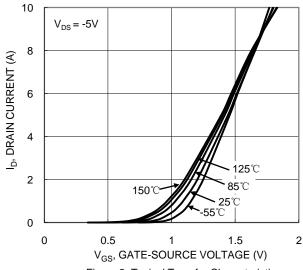


Figure 2. Typical Transfer Characteristic

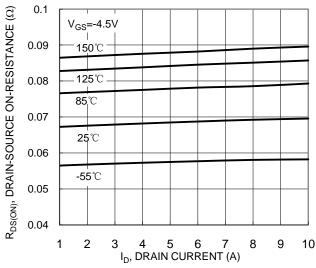


Figure 4. Typical On-Resistance vs. Drain Current and Junction Temperature

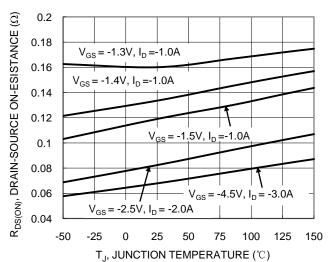


Figure 6. On-Resistance Variation with Junction Temperature



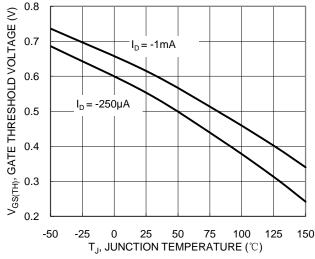
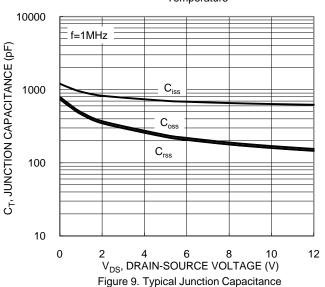


Figure 7. Gate Threshold Variation vs. Junction Temperature



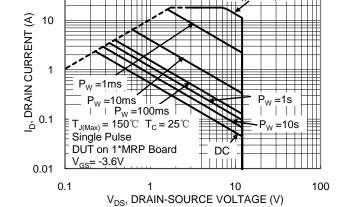
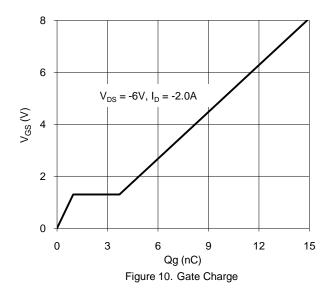


Figure 11. SOA, Safe Operation Area

10 $V_{GS} = 0V$ Is, SOURCE CURRENT (A) 8 6 4 $T_{J} = 85^{\circ}C$ $T_{J} = 125^{\circ}C$ $T_J = 25^{\circ}C$ 2 T_J = 150°C $T_{J} = -55^{\circ}C$ 0 $\begin{array}{cccc} 0.3 & 0.6 & 0.9 & 1.2 \\ V_{SD}, \text{SOURCE-DRAIN VOLTAGE (V)} \end{array}$ 0 1.5 Figure 8. Diode Forward Voltage vs. Current



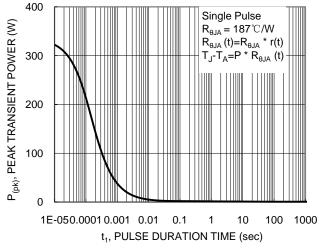


Figure 12. Single Pulse Maximum Power Dissipation

100

R_{DS(ON)} Limited



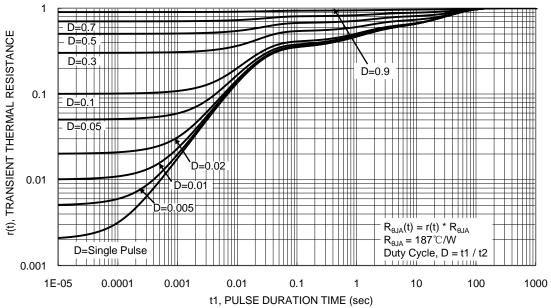


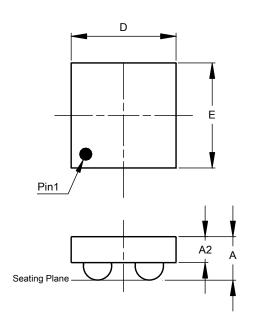
Figure 13. Transient Thermal Resistance

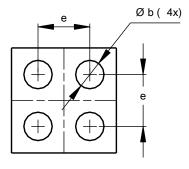


Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-WLB0808-4



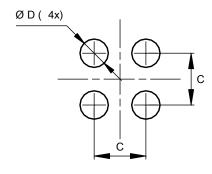


| X2-WLB0808-4 | | | | | | | |
|----------------------|--------|--------|-------|--|--|--|--|
| Dim | Min | Max | Тур | | | | |
| Α | | 0.375 | 0.350 | | | | |
| A2 | | - | 0.200 | | | | |
| b | 0.1971 | 0.2409 | 0.219 | | | | |
| D | 0.780 | 0.810 | 0.800 | | | | |
| Е | 0.780 | 0.810 | 0.800 | | | | |
| е | | | 0.400 | | | | |
| All Dimensions in mm | | | | | | | |

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-WLB0808-4



| Dimensions | Value (in mm) | | | |
|------------|------------------|--|--|--|
| С | 0.400 | | | |
| D | 0.219 | | | |



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